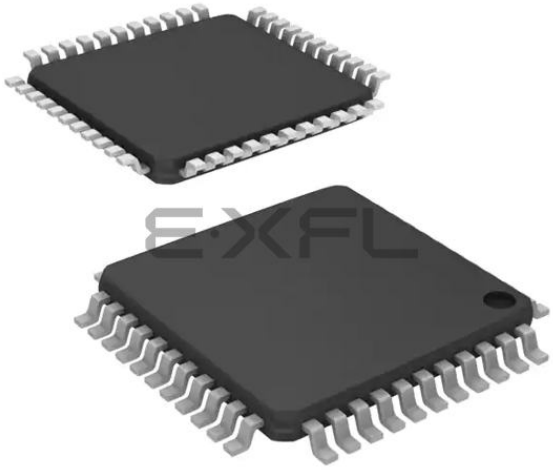

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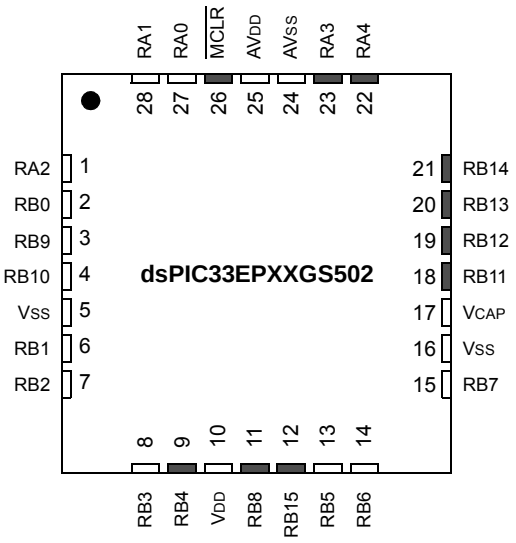
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	35
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 19x12b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep16gs504-e-pt

Pin Diagrams (Continued)

28-Pin QFN-S, UQFN



Pin	Pin Function	Pin	Pin Function
1	AN2/PGA1P3/PGA2P2/CMP1C/CMP2A/RA2	15	PGEC1/AN21/SDA1/**RP39**/RB7
2	AN3/PGA2P3/CMP1D/CMP2B/**RP32**/RB0	16	VSS
3	AN4/CMP2C/CMP3A/ISRC4/**RP41**/RB9	17	VCAP
4	AN5/CMP2D/CMP3B/ISRC3/**RP42**/RB10	18	TMS/PWM3H/**RP43**/RB11
5	Vss	19	TCK/PWM3L/**RP44**/**R**B12
6	OSC1/CLKI/AN6/CMP3C/CMP4A/ISRC2/**RP33**/RB1	20	PWM2H/**RP45**/RB13
7	OSC2/CLKO/AN7/PGA1N2/CMP3D/CMP4B/**RP34**/RB2	21	PWM2L/**RP46**/RB14
8	PGED2/AN18/DACOUT1/INT0/**RP35**/RB3	22	PWM1H/RA4
9	PGEC2/ADTRG31/EXTREF1/RP36/RB4	23	PWM1L/RA3
10	VDD	24	AVSS
11	PGED3/SDA2/FLT31/RP40/RB8	25	AVDD
12	PGEC3/SCL2/**RP47**/RB15	26	$\overline{\text{MCLR}}$
13	TDO/AN19/PGA2N2/**RP37**/RB5	27	AN0/PGA1P1/CMP1A/RA0
14	PGED1/TDI/AN20/SCL1/**RP38**/RB6	28	AN1/PGA1P2/PGA2P1/CMP1B/RA1

Legend: **Shaded pins** are up to 5 VDC tolerant.
RPn represents remappable peripheral functions. See Table 10-1 and Table 10-2 for the complete list of remappable sources.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name(1)	Pin Type	Buffer Type	PPS	Description
$\overline{MCLR}$	I/P	ST	No	Master Clear (Reset) input. This pin is an active-low Reset to the device.
AVDD	P	P	No	Positive supply for analog modules. This pin must be connected at all times.
AVSS	P	P	No	Ground reference for analog modules. This pin must be connected at all times.
VDD	P	—	No	Positive supply for peripheral logic and I/O pins.
VCAP	P	—	No	CPU logic filter capacitor connection.
VSS	P	—	No	Ground reference for logic and I/O pins.

Legend: CMOS = CMOS compatible input or output
Analog = Analog input
P = Power
ST = Schmitt Trigger input with CMOS levels
O = Output
I = Input
PPS = Peripheral Pin Select
TTL = TTL input buffer

1: Not all pins are available in all packages variants. See the **"Pin Diagrams"** section for pin availability.

2: These pins are dedicated on 64-pin devices.

REGISTER 3-2: CORCON: CORE CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-0
VAR	—	US1	US0	EDT(1)	DL2	DL1	DL0
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-0	R/C-0	R-0	R/W-0	R/W-0
SATA	SATB	SATDW	ACCSAT	IPL3(2)	SFA	RND	IF
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **VAR:** Variable Exception Processing Latency Control bit
1 = Variable exception processing is enabled
0 = Fixed exception processing is enabled

bit 14 **Unimplemented:** Read as '0'

bit 13-12 **US<1:0>:** DSP Multiply Unsigned/Signed Control bits
11 = Reserved
10 = DSP engine multiplies are mixed-sign
01 = DSP engine multiplies are unsigned
00 = DSP engine multiplies are signed

bit 11 **EDT:** Early DO Loop Termination Control bit(1)
1 = Terminates executing DO loop at the end of current loop iteration
0 = No effect

bit 10-8 **DL<2:0>:** DO Loop Nesting Level Status bits
111 = 7 DO loops are active
•
•
•
001 = 1 DO loop is active
000 = 0 DO loops are active

bit 7 **SATA:** ACCA Saturation Enable bit
1 = Accumulator A saturation is enabled
0 = Accumulator A saturation is disabled

bit 6 **SATB:** ACCB Saturation Enable bit
1 = Accumulator B saturation is enabled
0 = Accumulator B saturation is disabled

bit 5 **SATDW:** Data Space Write from DSP Engine Saturation Enable bit
1 = Data Space write saturation is enabled
0 = Data Space write saturation is disabled

bit 4 **ACCSAT:** Accumulator Saturation Mode Select bit
1 = 9.31 saturation (super saturation)
0 = 1.31 saturation (normal saturation)

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit 3(2)
1 = CPU Interrupt Priority Level is greater than 7
0 = CPU Interrupt Priority Level is 7 or less

Note 1: This bit is always read as '0'.
2: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

4.0 MEMORY ORGANIZATION

Note: This data sheet summarizes the features of the dsPIC33EPXXGS50X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"dsPIC33E/PIC24E Program Memory"** (DS70000613) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

The dsPIC33EPXXGS50X family architecture features separate program and data memory spaces, and buses. This architecture also allows the direct access of program memory from the Data Space (DS) during code execution.

4.1 Program Address Space

The program address memory space of the dsPIC33EPXXGS50X family devices is 4M instructions. The space is addressable by a 24-bit value derived either from the 23-bit PC during program execution, or from table operation or Data Space remapping, as described in **Section 4.9 "Interfacing Program and Data Memory Spaces"**.

User application access to the program memory space is restricted to the lower half of the address range (0x000000 to 0x7FFFFF). The exception is the use of TBLRD operations, which use TBLPAG<7> to permit access to calibration data and Device ID sections of the configuration memory space.

The program memory maps for the dsPIC33EP16/32GS50X and dsPIC33EP64GS50X devices not operating in Dual Partition mode, are shown in Figure 4-1 through Figure 4-3.

The dsPIC33EP64GS50X devices can operate in a Dual Partition Flash Program Memory mode, where the user program Flash memory is arranged as two separate address spaces, one for each of the Flash partitions. The Active Partition always starts at address, 0x000000, and contains half of the available Flash memory (32K). The Inactive Partition always starts at address, 0x400000, and implements the remaining half of Flash memory. As shown in Figure 4-4, the Active and Inactive Partitions are identical and both contain unique copies of the Reset vector, Interrupt Vector Tables (IVT and AIVT if enabled) and the Flash Configuration Words.

4.2 Unique Device Identifier (UDID)

All (16-bit devices) family devices are individually encoded during final manufacturing with a Unique Device Identifier or UDID. This feature allows for manufacturing traceability of Microchip Technology devices in applications where this is a requirement. It may also be used by the application manufacturer for any number of things that may require unique identification, such as:

- Tracking the device
- Unique serial number
- Unique security key

The UDID comprises five 24-bit program words. When taken together, these fields form a unique 120-bit identifier.

The UDID is stored in five read-only locations, located between 800F00h and 800F08h in the device configuration space. Table 4-1 lists the addresses of the identifier words and shows their contents.

TABLE 4-1: UDID ADDRESSES

Name	Address	Bits 23:16	Bits 15:8	Bits 7:0
UDID1	800F00	UDID Word 1		
UDID2	800F02	UDID Word 2		
UDID3	800F04	UDID Word 3		
UDID4	800F06	UDID Word 4		
UDID5	800F08	UDID Word 5		

4.9.1 DATA ACCESS FROM PROGRAM MEMORY USING TABLE INSTRUCTIONS

The TBLRDL and TBLWTL instructions offer a direct method of reading or writing the lower word of any address within the Program Space without going through Data Space. The TBLRDH and TBLWTH instructions are the only method to read or write the upper 8 bits of a Program Space word as data.

The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to Data Space addresses. Program memory can thus be regarded as two 16-bit wide word address spaces, residing side by side, each with the same address range. TBLRDL and TBLWTL access the space that contains the least significant data word. TBLRDH and TBLWTH access the space that contains the upper data byte.

Two table instructions are provided to move byte or word-sized (16-bit) data to and from Program Space. Both function as either byte or word operations.

- TBLRDL (Table Read Low):
  - In Word mode, this instruction maps the lower word of the Program Space location (P<15:0>) to a data address (D<15:0>)
  - In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when Byte Select is '1'; the lower byte is selected when it is '0'.
- TBLRDH (Table Read High):
  - In Word mode, this instruction maps the entire upper word of a program address (P<23:16>) to a data address. The 'phantom' byte (D<15:8>) is always '0'.
  - In Byte mode, this instruction maps the upper or lower byte of the program word to D<7:0> of the data address in the TBLRDL instruction. The data is always '0' when the upper 'phantom' byte is selected (Byte Select = 1).

In a similar fashion, two table instructions, TBLWTH and TBLWTL, are used to write individual bytes or words to a Program Space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Page register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user application and configuration spaces. When TBLPAG<7> = 0, the table page is located in the user memory space. When TBLPAG<7> = 1, the page is located in configuration space.

FIGURE 4-15: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS

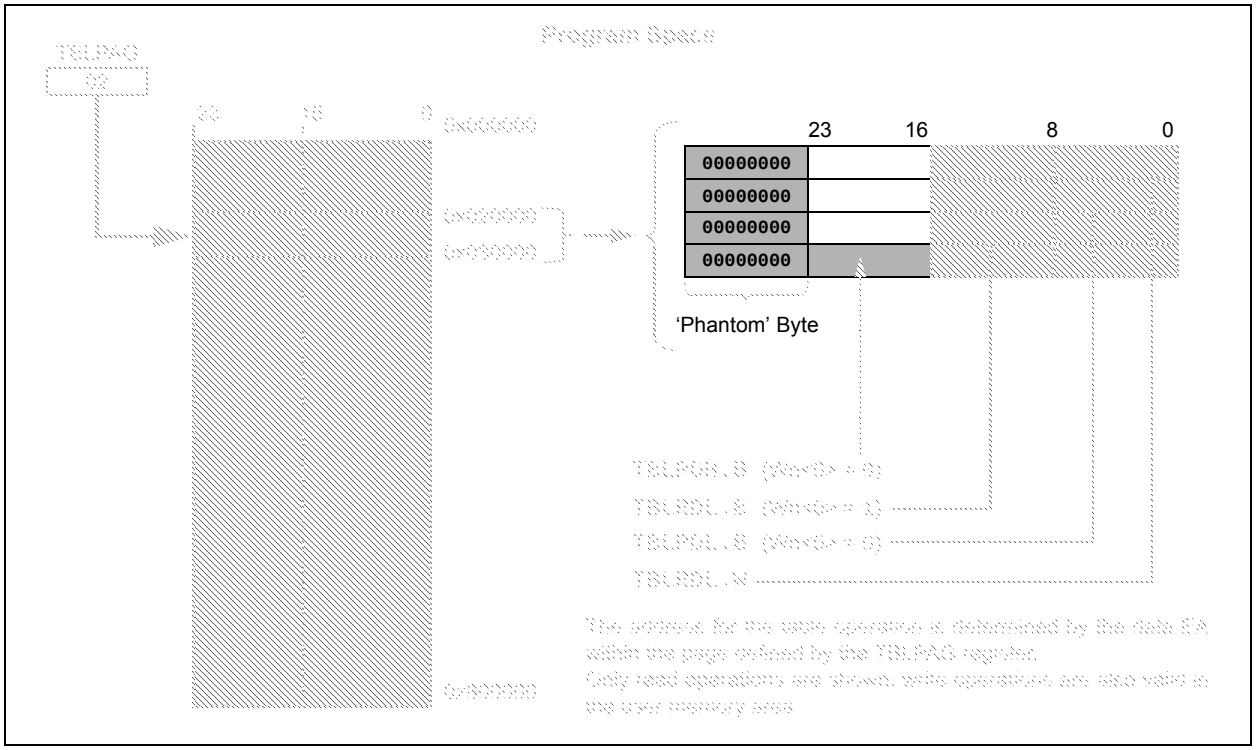
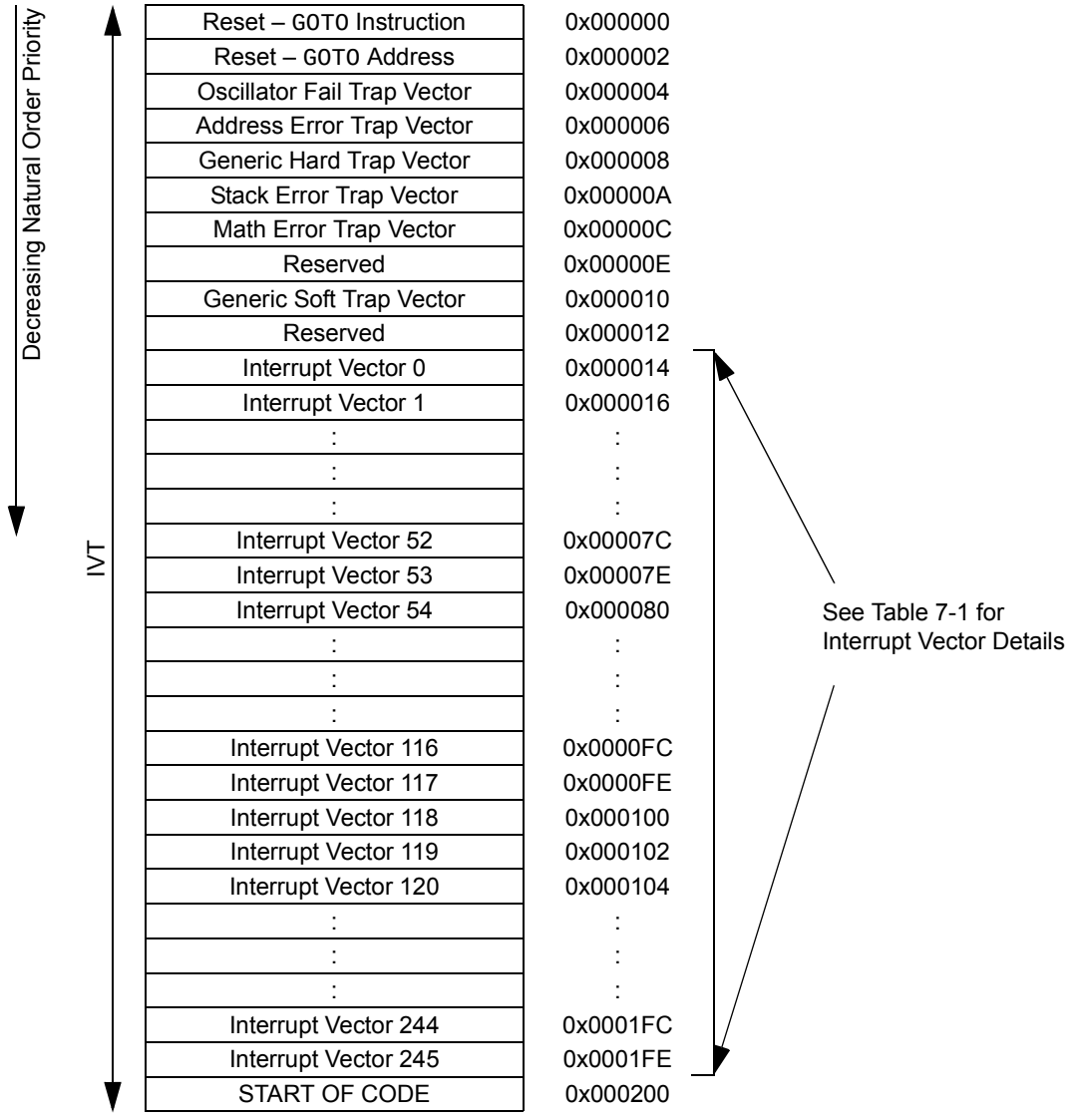


FIGURE 7-1: dsPIC33EPXXGS50X FAMILY INTERRUPT VECTOR TABLE



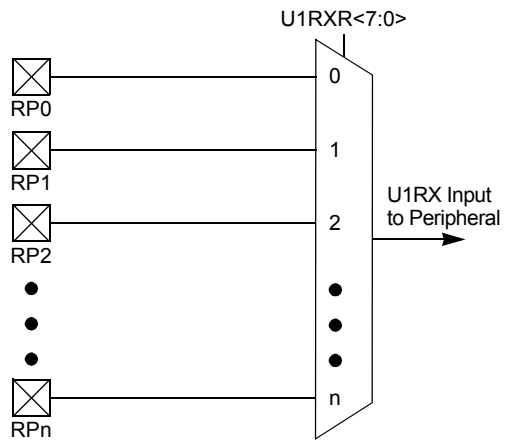
Note: In Dual Partition modes, each partition has a dedicated Interrupt Vector Table.

10.4.4 INPUT MAPPING

The inputs of the Peripheral Pin Select options are mapped on the basis of the peripheral. That is, a control register associated with a peripheral dictates the pin it will be mapped to. The RPINRx registers are used to configure peripheral input mapping (see Register 10-1 through Register 10-19). Each register contains sets of 8-bit fields, with each set associated with one of the remappable peripherals. Programming a given peripheral's bit field with an appropriate 8-bit value maps the RPn pin with the corresponding value to that peripheral. For any given device, the valid range of values for any bit field corresponds to the maximum number of Peripheral Pin Selections supported by the device.

For example, Figure 10-2 illustrates remappable pin selection for the U1RX input.

FIGURE 10-2: REMAPPABLE INPUT FOR U1RX



Note: For input only, Peripheral Pin Select functionality does not have priority over TRISx settings. Therefore, when configuring an RPn pin for input, the corresponding bit in the TRISx register must also be configured for input (set to '1').

10.4.4.1 Virtual Connections

The dsPIC33EPXXGS50X devices support six virtual RPn pins (RP176-RP181), which are identical in functionality to all other RPn pins, with the exception of pinouts. These six pins are internal to the devices and are not connected to a physical device pin.

These pins provide a simple way for inter-peripheral connection without utilizing a physical pin. For example, the output of the analog comparator can be connected to RP176 and the PWM Fault input can be configured for RP176 as well. This configuration allows the analog comparator to trigger PWM Faults without the use of an actual physical pin on the device.

10.5 I/O Helpful Tips

1. In some cases, certain pins, as defined in Table 26-11 under “Injection Current”, have internal protection diodes to VDD and VSS. The term, “Injection Current”, is also referred to as “Clamp Current”. On designated pins, with sufficient external current-limiting precautions by the user, I/O pin input voltages are allowed to be greater or less than the data sheet absolute maximum ratings, with respect to the VSS and VDD supplies. Note that when the user application forward biases either of the high or low side internal input clamp diodes, that the resulting current being injected into the device, that is clamped internally by the VDD and VSS power rails, may affect the ADC accuracy by four to six counts.
2. I/O pins that are shared with any analog input pin (i.e., ANx) are always analog pins by default after any Reset. Consequently, configuring a pin as an analog input pin automatically disables the digital input pin buffer and any attempt to read the digital input level by reading PORTx or LATx will always return a ‘0’, regardless of the digital logic level on the pin. To use a pin as a digital I/O pin on a shared ANx pin, the user application needs to configure the Analog Pin Configuration registers in the I/O ports module (i.e., ANSELx) by setting the appropriate bit that corresponds to that I/O port pin to a ‘0’.

Note:	Although it is not possible to use a digital input pin when its analog function is enabled, it is possible to use the digital I/O output function, TRISx = 0x0, while the analog function is also enabled. However, this is not recommended, particularly if the analog input is connected to an external analog voltage source, which would create signal contention between the analog signal and the output pin driver.

3. Most I/O pins have multiple functions. Referring to the device pin diagrams in this data sheet, the priorities of the functions allocated to any pins are indicated by reading the pin name from left-to-right. The left most function name takes precedence over any function to its right in the naming convention. For example: AN16/T2CK/T7CK/RC1; this indicates that AN16 is the highest priority in this example and will supersede all other functions to its right in the list. Those other functions to its right, even if enabled, would not work as long as any other function to its left was enabled. This rule applies to all of the functions listed for a given pin.
4. Each pin has an internal weak pull-up resistor and pull-down resistor that can be configured using the CNPUx and CNPDx registers, respectively. These resistors eliminate the need for external resistors in certain applications. The internal pull-up is up to ~(VDD – 0.8), not VDD. This value is still above the minimum VIH of CMOS and TTL devices.
5. When driving LEDs directly, the I/O pin can source or sink more current than what is specified in the VOH/IOH and VOL/IOL DC characteristics specification. The respective IOH and IOL current rating only applies to maintaining the corresponding output at or above the VOH, and at or below the VOL levels. However, for LEDs, unlike digital inputs of an externally connected device, they are not governed by the same minimum VIH/VIL levels. An I/O pin output can safely sink or source any current less than that listed in the Absolute Maximum Ratings in **Section 26.0 “Electrical Characteristics”**of this data sheet. For example:

   VOH = 2.4v @ IOH = -8 mA and VDD = 3.3V

   The maximum output current sourced by any 8 mA I/O pin = 12 mA.

   LED source current < 12 mA is technically permitted. Refer to the VOH/IOH graphs in **Section 27.0 “DC and AC Device Characteristics Graphs”** for additional information.

REGISTER 10-5: RPINR7: PERIPHERAL PIN SELECT INPUT REGISTER 7

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IC2R7	IC2R6	IC2R5	IC2R4	IC2R3	IC2R2	IC2R1	IC2R0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IC1R7	IC1R6	IC1R5	IC1R4	IC1R3	IC1R2	IC1R1	IC1R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **IC2R<7:0>:** Assign Input Capture 2 (IC2) to the Corresponding RPn Pin bits

10110101 = Input tied to RP181
10110100 = Input tied to RP180
•
•
•
00000001 = Input tied to RP1
00000000 = Input tied to Vss

bit 7-0 **IC1R<7:0>:** Assign Input Capture 1 (IC1) to the Corresponding RPn Pin bits

10110101 = Input tied to RP181
10110100 = Input tied to RP180
•
•
•
00000001 = Input tied to RP1
00000000 = Input tied to Vss

15.0 HIGH-SPEED PWM

Note: This data sheet summarizes the features of the dsPIC33EPXXGS50X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"High-Speed PWM Module"** (DS70000323) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

The high-speed PWM module on dsPIC33EPXXGS50X devices supports a wide variety of PWM modes and output formats. This PWM module is ideal for power conversion applications, such as:

- AC/DC Converters
- DC/DC Converters
- Power Factor Correction
- Uninterruptible Power Supply (UPS)
- Inverters
- Battery Chargers
- Digital Lighting

15.1 Features Overview

The high-speed PWM module incorporates the following features:

- Five PWMx Generators with Two Outputs per Generator
- Two Master Time Base Modules
- Individual Time Base and Duty Cycle for Each PWM Output
- Duty Cycle, Dead Time, Phase Shift and a Frequency Resolution of 1.04 ns
- Independent Fault and Current-Limit Inputs
- Redundant Output
- True Independent Output
- Center-Aligned PWM mode
- Output Override Control
- Chop mode (also known as Gated mode)
- Special Event Trigger
- Dual Trigger from PWMx to Analog-to-Digital Converter (ADC)
- PWMxL and PWMxH Output Pin Swapping
- Independent PWMx Frequency, Duty Cycle and Phase-Shift Changes
- Enhanced Leading-Edge Blanking (LEB) Functionality
- PWM Capture Functionality

Note: Duty cycle, dead time, phase shift and frequency resolution is 8.32 ns in Center-Aligned PWM mode.

Figure 15-1 conceptualizes the PWM module in a simplified block diagram. Figure 15-2 illustrates how the module hardware is partitioned for each PWMx output pair for the Complementary PWM mode.

The PWM module contains five PWM generators. The module has up to 10 PWMx output pins: PWM1H/PWM1L through PWM5H/PWM5L. For complementary outputs, these 10 I/O pins are grouped into high/low pairs.

15.2 Feature Description

The PWM module is designed for applications that require:

- High resolution at high PWM frequencies
- The ability to drive Standard, Edge-Aligned, Center-Aligned Complementary mode and Push-Pull mode outputs
- The ability to create multiphase PWM outputs

Two common, medium power converter topologies are push-pull and half-bridge. These designs require the PWM output signal to be switched between alternate pins, as provided by the Push-Pull PWM mode.

Phase-shifted PWM describes the situation where each PWM generator provides outputs, but the phase relationship between the generator outputs is specifiable and changeable.

Multiphase PWM is often used to improve DC/DC converter load transient response, and reduce the size of output filter capacitors and inductors. Multiple DC/DC converters are often operated in parallel, but phase shifted in time. A single PWM output, operating at 250 kHz, has a period of 4 μs but an array of four PWM channels, staggered by 1 μs each, yields an effective switching frequency of 1 MHz. Multiphase PWM applications typically use a fixed-phase relationship.

Variable phase PWM is useful in Zero Voltage Transition (ZVT) power converters. Here, the PWM duty cycle is always 50% and the power flow is controlled by varying the relative phase shift between the two PWM generators.

18.3 UART Control Registers

REGISTER 18-1: UxMODE: UARTx MODE REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
UARTEN(1)	—	USIDL	IREN(2)	RTSMD	—	UEN1	UEN0
bit 15							bit 8

R/W-0, HC	R/W-0	R/W-0, HC	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WAKE	LPBACK	ABAUD	URXINV	BRGH	PDSEL1	PDSEL0	STSEL
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **UARTEN:** UARTx Enable bit(1)
- 1 = UARTx is enabled; all UARTx pins are controlled by UARTx as defined by UEN<1:0>
- 0 = UARTx is disabled; all UARTx pins are controlled by PORT latches; UARTx power consumption is minimal

bit 14 **Unimplemented:** Read as '0'

bit 13 **USIDL:** UARTx Stop in Idle Mode bit
- 1 = Discontinues module operation when device enters Idle mode
- 0 = Continues module operation in Idle mode

bit 12 **IREN:** IrDA® Encoder and Decoder Enable bit(2)
- 1 = IrDA encoder and decoder are enabled
- 0 = IrDA encoder and decoder are disabled

bit 11 **RTSMD:** Mode Selection for $\overline{\text{UxRTS}}$ Pin bit
- 1 = $\overline{\text{UxRTS}}$ pin is in Simplex mode
- 0 = $\overline{\text{UxRTS}}$ pin is in Flow Control mode

bit 10 **Unimplemented:** Read as '0'

bit 9-8 **UEN<1:0>:** UARTx Pin Enable bits
- 11 = UxTX, UxRX and BCLKx pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by PORT latches
- 10 = UxTX, UxRX, $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins are enabled and used
- 01 = UxTX, UxRX and $\overline{\text{UxRTS}}$ pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by PORT latches
- 00 = UxTX and UxRX pins are enabled and used; $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$/BCLKx pins are controlled by PORT latches

bit 7 **WAKE:** Wake-up on Start Bit Detect During Sleep Mode Enable bit
- 1 = UARTx continues to sample the UxRX pin, interrupt is generated on the falling edge; bit is cleared in hardware on the following rising edge
- 0 = No wake-up is enabled

bit 6 **LPBACK:** UARTx Loopback Mode Select bit
- 1 = Enables Loopback mode
- 0 = Loopback mode is disabled

Note 1: Refer to **"Universal Asynchronous Receiver Transmitter (UART)"** (DS70000582) in the *"dsPIC33/PIC24 Family Reference Manual"* for information on enabling the UARTx module for receive or transmit operation.

2: This feature is only available for the 16x BRG mode (BRGH = 0).

REGISTER 19-4: ADCON2H: ADC CONTROL REGISTER 2 HIGH

R-0, HSC	R-0, HSC	r-0	r-0	r-0	r-0	R/W-0	R/W-0
REFRDY	REFERR	—	—	—	—	SHRSAMC9	SHRSAMC8
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SHRSAMC7	SHRSAMC6	SHRSAMC5	SHRSAMC4	SHRSAMC3	SHRSAMC2	SHRSAMC1	SHRSAMC0
bit 7							bit 0

Legend:	r = Reserved bit	U = Unimplemented bit, read as ‘0’	
R = Readable bit	W = Writable bit	HSC = Hardware Settable/Clearable bit	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **REFRDY:** Band Gap and Reference Voltage Ready Flag bit
1 = Band gap is ready
0 = Band gap is not ready

bit 14 **REFERR:** Band Gap or Reference Voltage Error Flag bit
1 = Band gap was removed after the ADC module was enabled (ADON = 1)
0 = No band gap error was detected

bit 13-10 **Reserved:** Maintain as ‘0’

bit 9-0 **SHRSAMC<9:0>:** Shared ADC Core Sample Time Selection bits
These bits specify the number of shared ADC Core Clock Periods (TADCORE) for the shared ADC core sample time.
1111111111 = 1025 TADCORE
•
•
•
0000000001 = 3 TADCORE
0000000000 = 2 TADCORE

REGISTER 19-11: ADCOREXL: DEDICATED ADC CORE x CONTROL REGISTER LOW (x = 0 to 3)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	SAMC<9:8>	
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SAMC<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-10 **Unimplemented:** Read as '0'

bit 9-0 **SAMC<9:0>:** Dedicated ADC Core x Conversion Delay Selection bits

These bits determine the time between the trigger event and the start of conversion in the number of the Core Clock Periods (TADCORE). During this time, the ADC Core x still continues sampling. This feature is enabled by the SAMCxEN bits in the ADCON4L register.

1111111111 = 1025 TADCORE

•

•

•

0000000001 = 3 TADCORE

0000000000 = 2 TADCORE

22.3 Current Source Control Register

REGISTER 22-1: ISRCCON: CONSTANT-CURRENT SOURCE CONTROL REGISTER

R/W-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
ISRCEN	—	—	—	—	OUTSEL2	OUTSEL1	OUTSEL0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	ISRCCAL5	ISRCCAL4	ISRCCAL3	ISRCCAL2	ISRCCAL1	ISRCCAL0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **ISRCEN:** Constant-Current Source Enable bit
1 = Current source is enabled
0 = Current source is disabled

bit 14-11 **Unimplemented:** Read as ‘0’

bit 10-8 **OUTSEL<2:0>:** Output Constant-Current Select bits
111 = Reserved
110 = Reserved
101 = Reserved
100 = Input pin, ISRC4 (AN4)
011 = Input pin, ISRC3 (AN5)
010 = Input pin, ISRC2 (AN6)
001 = Input pin, ISRC1 (AN12)
000 = No output is selected

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **ISRCCAL<5:0>:** Constant-Current Source Calibration bits
The calibration value must be copied from Flash address, 0x800E78, into these bits before the module is enabled. Refer to the calibration data address table (Table 23-3) in **Section 23.0 “Special Features”** for more information.

TABLE 26-14: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
		Program Flash Memory					
D130	EP	Cell Endurance	10,000	—	—	E/W	-40°C to +125°C
D131	VPR	VDD for Read	3.0	—	3.6	V	
D132b	VPEW	VDD for Self-Timed Write	3.0	—	3.6	V	
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated, -40°C to +125°C
D135	IDDP	Supply Current during Programming(2)	—	10	—	mA	
D136	IPEAK	Instantaneous Peak Current During Start-up	—	—	150	mA	
D137a	TPE	Page Erase Time	19.7	—	20.1	ms	TPE = 146893 FRC cycles, TA = +85°C **(Note 3)**
D137b	TPE	Page Erase Time	19.5	—	20.3	ms	TPE = 146893 FRC cycles, TA = +125°C **(Note 3)**
D138a	TWW	Word Write Cycle Time	46.5	—	47.3	µs	TWW = 346 FRC cycles, TA = +85°C **(Note 3)**
D138b	TWW	Word Write Cycle Time	46.0	—	47.9	µs	TWW = 346 FRC cycles, TA = +125°C **(Note 3)**
D139a	TRW	Row Write Time	667	—	679	µs	TRW = 4965 FRC cycles, TA = +85°C **(Note 3)**
D139b	TRW	Row Write Time	660	—	687	µs	TRW = 4965 FRC cycles, TA = +125°C **(Note 3)**

Note 1: Data in “Typ.” column is at 3.3V, +25°C unless otherwise stated.

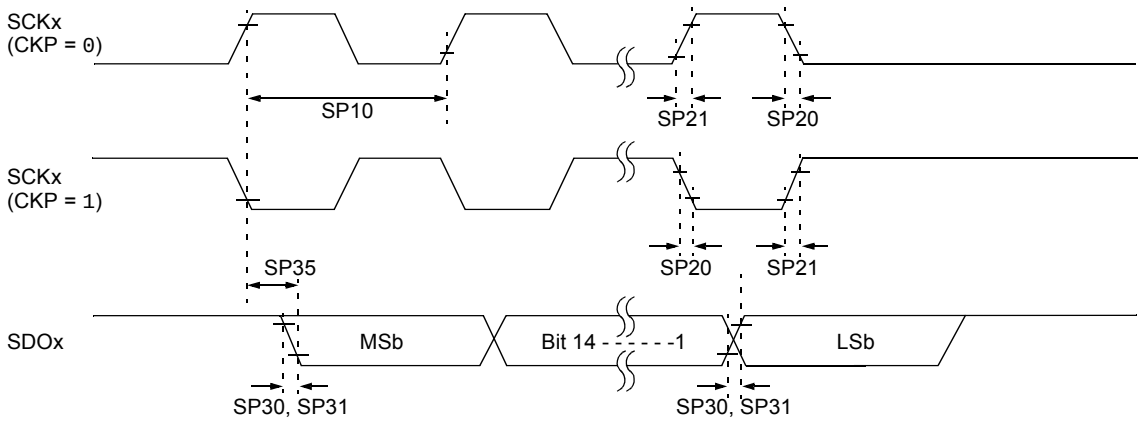
2: Parameter characterized but not tested in manufacturing.

3: Other conditions: FRC = 7.37 MHz, TUN<5:0> = `011111` (for Minimum), TUN<5:0> = `100000` (for Maximum). This parameter depends on the FRC accuracy (see Table 26-20) and the value of the FRC Oscillator Tuning register (see Register 8-4). For complete details on calculating the Minimum and Maximum time, see **Section 5.3 “Programming Operations”**.

TABLE 26-31: SPIx MAXIMUM DATA/CLOCK RATE SUMMARY

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
15 MHz	Table 26-31	—	—	0,1	0,1	0,1
9 MHz	—	Table 26-32	—	1	0,1	1
9 MHz	—	Table 26-33	—	0	0,1	1
15 MHz	—	—	Table 26-34	1	0	0
11 MHz	—	—	Table 26-35	1	1	0
15 MHz	—	—	Table 26-36	0	1	0
11 MHz	—	—	Table 26-37	0	0	0

FIGURE 26-11: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-36: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCKx Input Frequency	—	—	Lesser of: FP or 11	MHz	**(Note 3)**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid After SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH, TscL2ssH	$\overline{SSx}$ ↑ after SCKx Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	SDOx Data Output Valid after $\overline{SSx}$ Edge	—	—	50	ns	

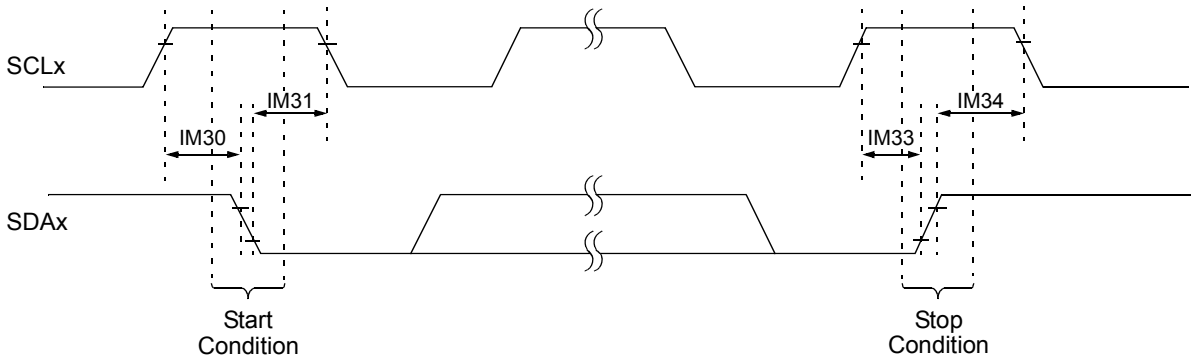
Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ." column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 91 ns. Therefore, the SCKx clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 26-19: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)



Note: Refer to Figure 26-1 for load conditions.

FIGURE 26-20: I2Cx BUS DATA TIMING CHARACTERISTICS (MASTER MODE)

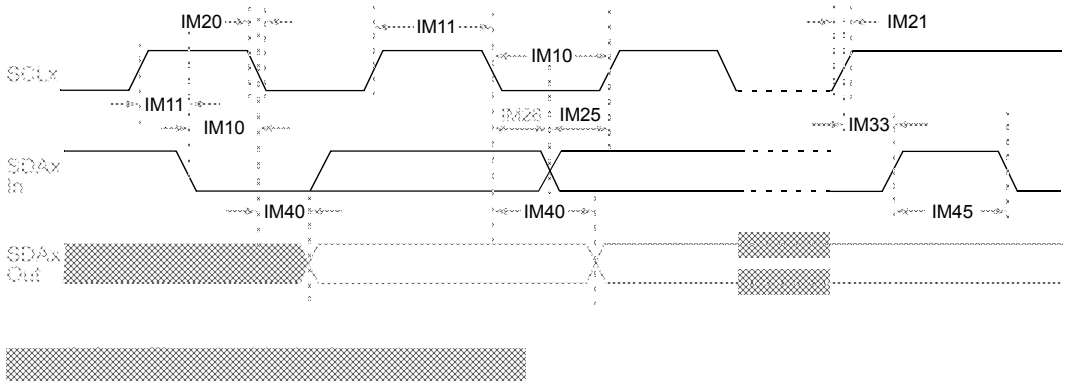


FIGURE 26-23: UARTx MODULE I/O TIMING CHARACTERISTICS

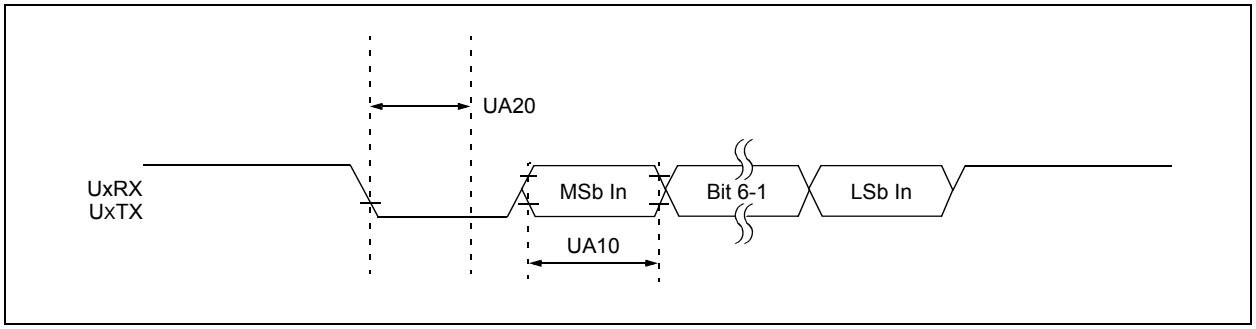


TABLE 26-41: UARTx MODULE I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C				
Param No.	Symbol	Characteristic(1)	Min.	Typ.(2)	Max.	Units	Conditions
UA10	TUABAUD	UARTx Baud Time	66.67	—	—	ns	
UA11	FBAUD	UARTx Baud Frequency	—	—	15	Mbps	
UA20	TCWF	Start Bit Pulse Width to Trigger UARTx Wake-up	500	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ." column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 26-42: ANALOG CURRENT SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C				
Param No.	Symbol	Characteristic(1)	Min.	Typ.(2)	Max.	Units	Conditions
AVD01	IDD	Analog Modules Current Consumption	—	9	—	mA	Characterized data with the following modules enabled: APLL, 5 ADC Cores, 2 PGAs and 4 Analog Comparators

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ." column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

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